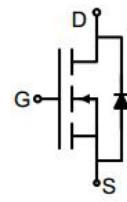
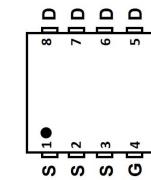


N-Channel Enhancement Mode Power MOSFET

<p>Description</p> <p>The GT020N04D5 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.</p> <p>General Features</p> <ul style="list-style-type: none"> ● V_{DS} 40V ● I_D (at $V_{GS} = 10V$) 138A ● $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 2mΩ ● $R_{DS(ON)}$ (at $V_{GS} = 4.5V$) < 2.8mΩ ● 100% Avalanche Tested ● RoHS Compliant <p>Application</p> <ul style="list-style-type: none"> ● Power switch ● DC/DC converters 	 <p>Schematic diagram</p>  <p>pin assignment</p>  <p>DFN5X6-8L</p>
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Ordering Information			
Device	Package	Marking	Packaging
GT020N04D5	DFN5X6-8L	GT020N04	5000pcs/Reel

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted				
Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	40	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	138	A
	$T_C = 100^\circ\text{C}$		87	
Pulsed Drain Current	(note1)	I_{DM}	552	A
Gate-Source Voltage		V_{GS}	± 20	V
Power Dissipation		P_D	83	W
Single pulse avalanche energy	(note2)	E_{AS}	196	mJ
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 To 150	°C

Thermal Resistance				
Parameter		Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient		R_{thJA}	50	°C/W
Thermal Resistance, Junction-to-Case		R_{thJC}	1.5	°C/W

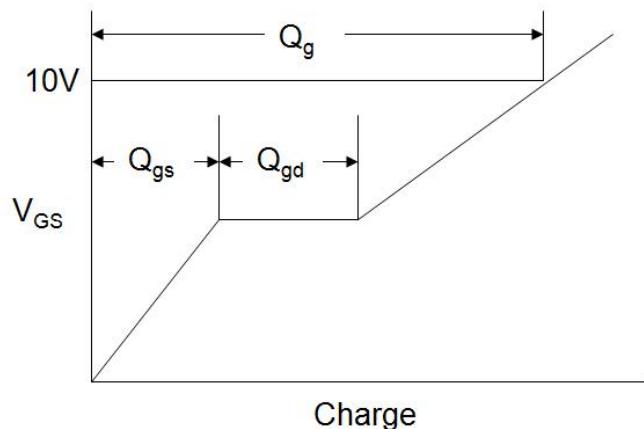
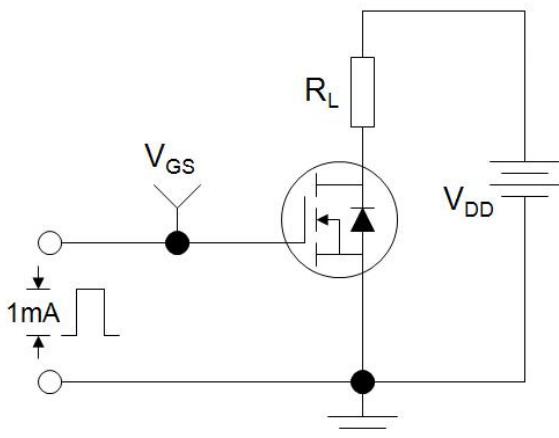
Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.2	1.6	2.4	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$	--	1.5	2.0	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 20\text{A}$	--	2.1	2.8	
Forward Transconductance	g_{FS}	$V_{\text{GS}} = 5\text{V}, I_D = 20\text{A}$	--	80	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 20\text{V}, f = 1\text{MHz}$	--	3100	--	pF
Output Capacitance	C_{oss}		--	1500	--	
Reverse Transfer Capacitance	C_{rss}		--	80	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = 20\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$	--	64	--	nC
Gate-Source Charge	Q_{gs}		--	12	--	
Gate-Drain Charge	Q_{gd}		--	11	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 20\text{V}, I_D = 20\text{A}, R_G = 0.5\Omega$	--	890	--	ns
Turn-on Rise Time	t_r		--	20	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	71	--	
Turn-off Fall Time	t_f		--	33	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	138	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 20\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V
Reverse Recovery Charge	Q_{rr}	$I_F = 20\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A}/\text{us}$	--	109	--	nC
Reverse Recovery Time	T_{rr}		--	30	--	ns

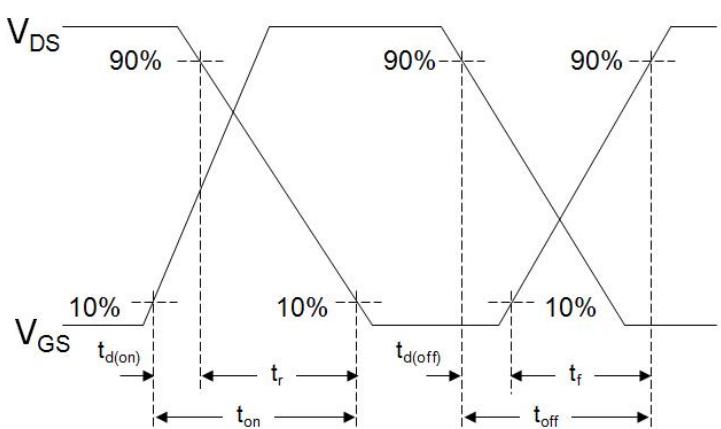
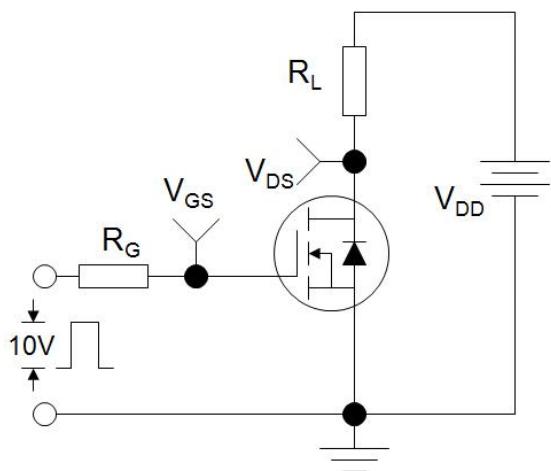
Notes

- Repetitive Rating: Pulse width limited by maximum junction temperature
- EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=40\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$
The table shows the minimum avalanche energy, which is 543mJ when the device is tested until failure
- Identical low side and high side switch with identical R_G

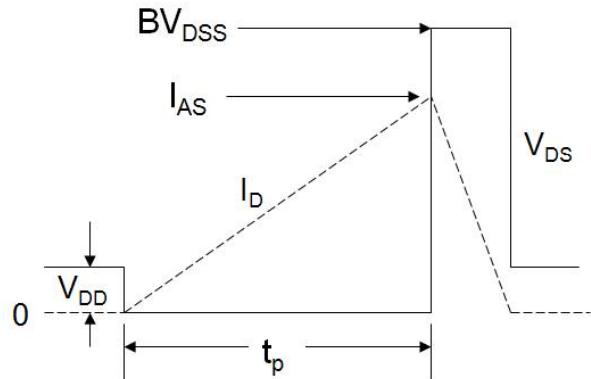
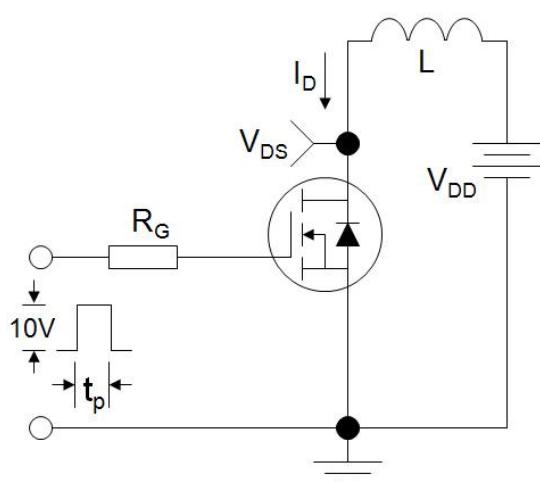
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

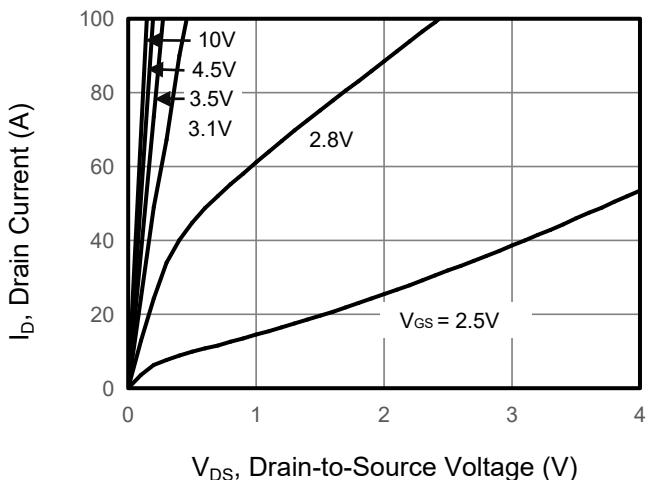


Figure 2. Transfer Characteristics

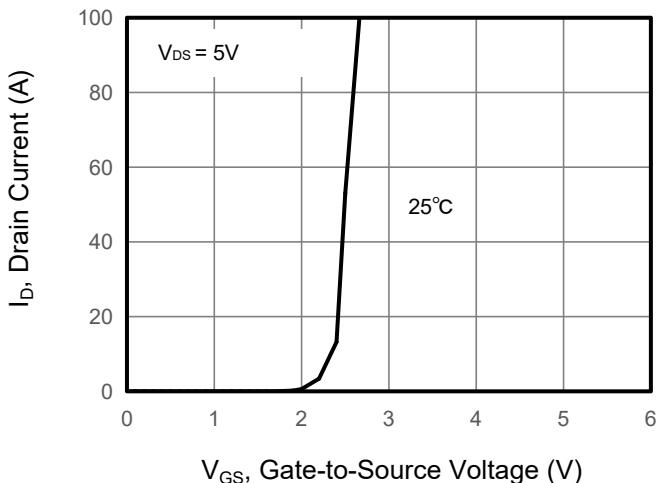


Figure 3. Drain Source On Resistance

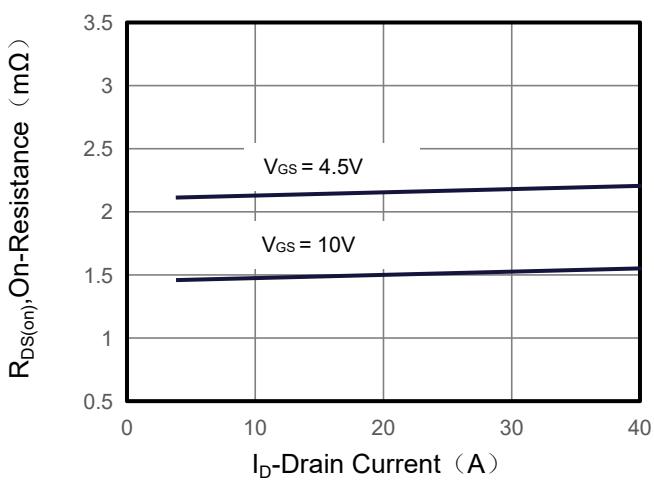


Figure 4. Gate Charge

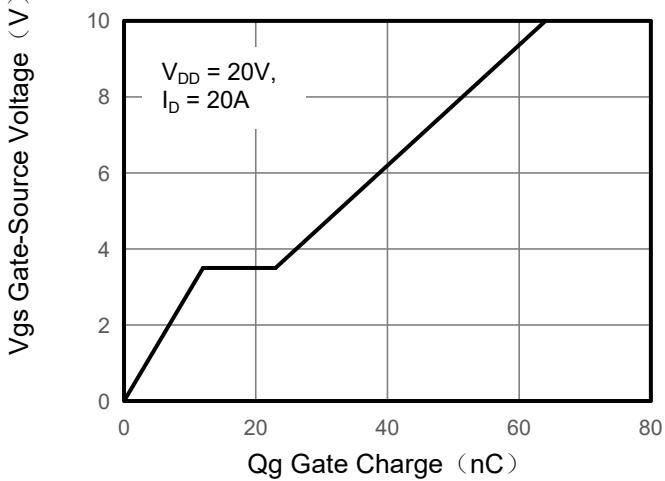


Figure 5. Capacitance

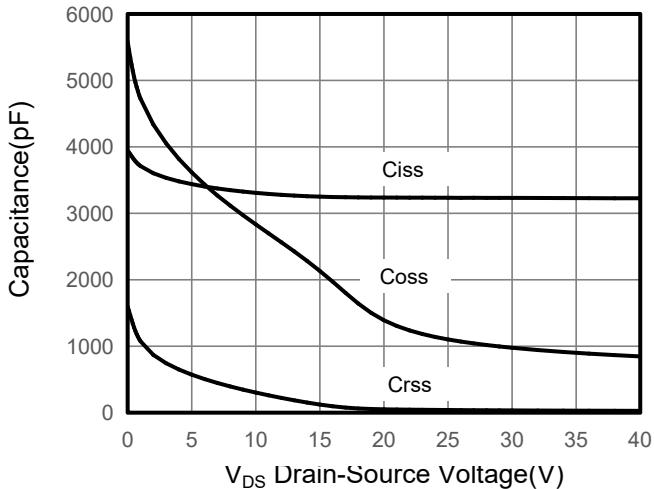
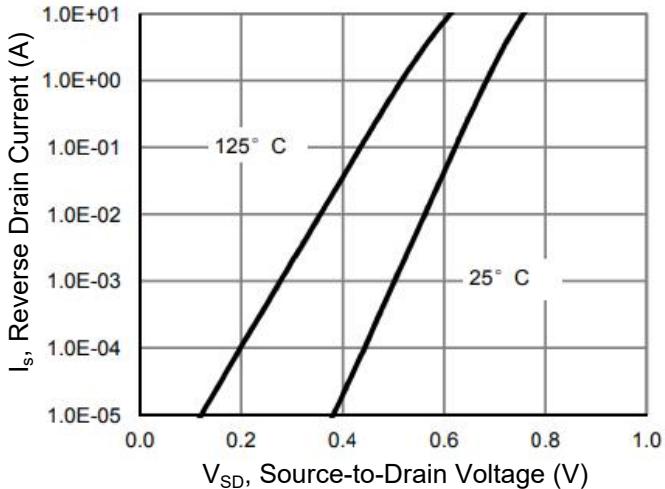


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

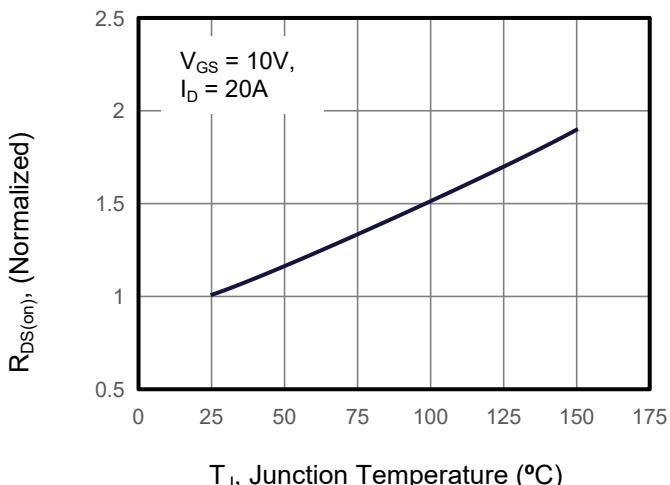


Figure 8. Safe Operation Area

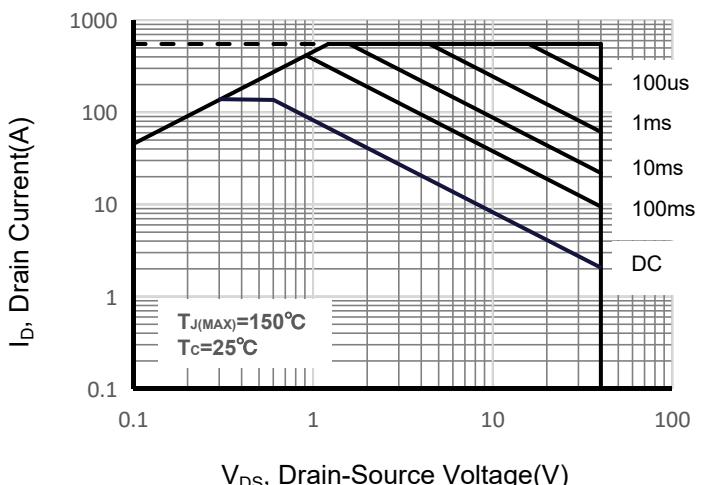


Figure 9. Maximum Continuous Drain Current vs Case Temperature

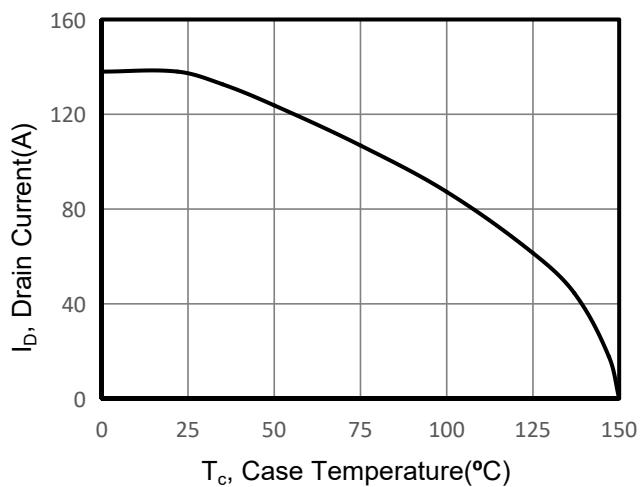
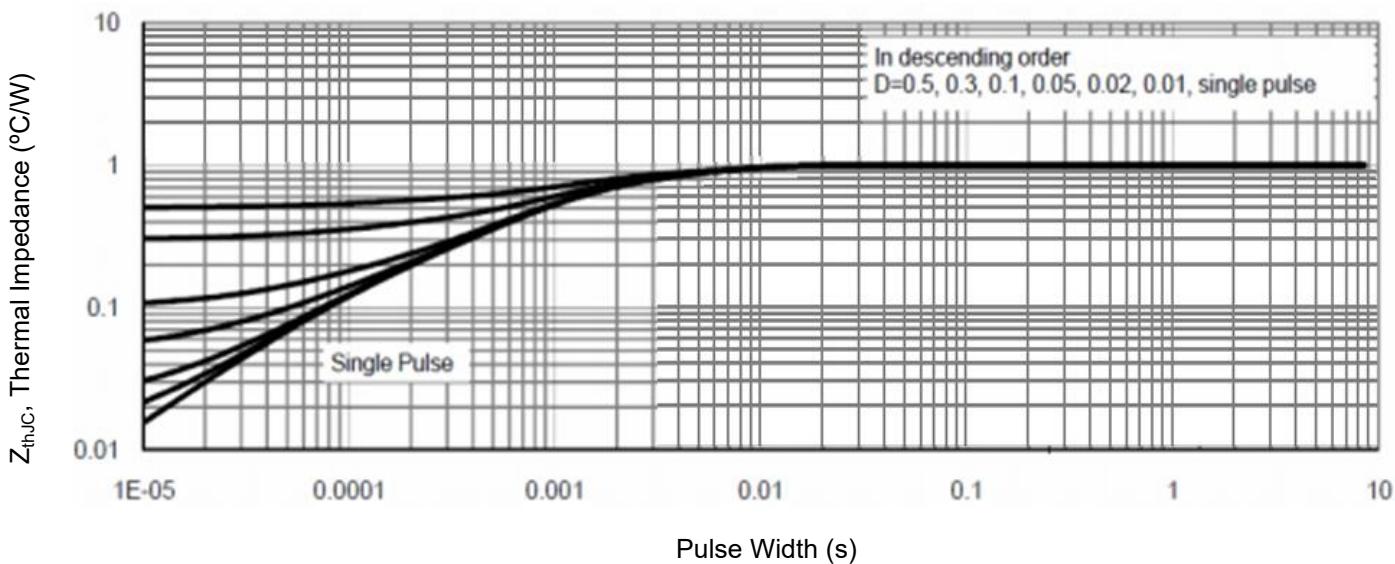
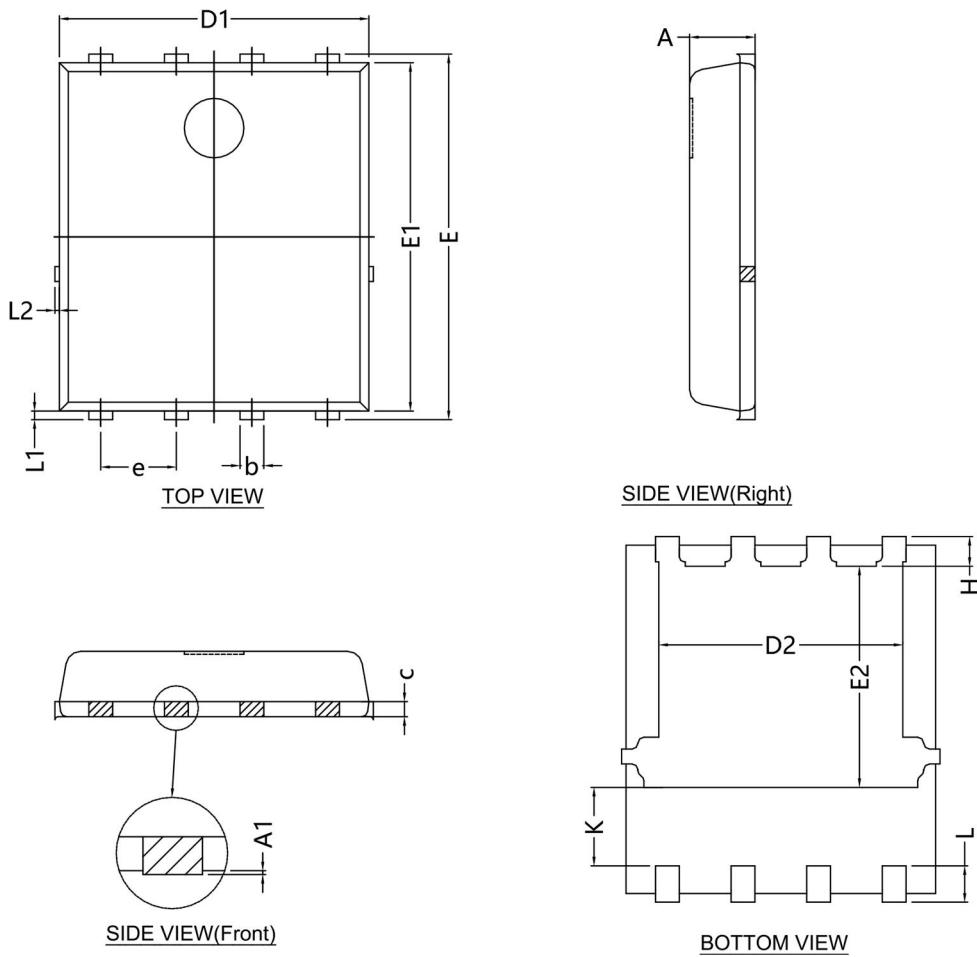


Figure 10. Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



DIM. SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	1.00	1.10	1.20
A1	0	---	0.05
b	0.30	0.40	0.50
c	0.20	0.25	0.30
D1	5.10	5.20	5.30
D2	3.90	4.10	4.25
E	6.00	6.15	6.30
E1	5.76	5.86	5.96
E2	3.52	3.72	3.92
e	1.27 BSC		
H	0.40	0.50	0.60
L	0.50	0.61	0.71
L1	0.05	0.15	0.25
L2	0.02	0.08	0.15
K	1.10	---	---